

Global Advanced Packaging Patent Intelligence 2026 – Strategic Analysis of Patent Landscape, Innovation Trends, Intellectual Property, Technology Domains, and Future Outlook

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Abstracts

The Global Advanced Packaging Patent Intelligence report provides an in-depth analysis of the intellectual property landscape within the global advanced packaging industry by evaluating patent filing activities, technology innovation trends, patent ownership, research activities, and emerging innovation domains. The report enables organizations to monitor technology leadership, assess competitive intellectual property positions, identify licensing opportunities, and support strategic decisions related to research, product development, and technology commercialization.

The study examines global patent portfolios across 2.5D packaging technologies, 3D packaging technologies, fan-out packaging technologies, chiplet and heterogeneous integration technologies, hybrid bonding and interconnect technologies, and next-generation advanced packaging technologies. It also analyzes patent filing trends, leading patent holders, technology domains, citation analysis, geographic distribution, and emerging innovators to provide actionable intelligence on the evolving advanced packaging innovation ecosystem.

The report further highlights patent commercialization opportunities, licensing activities, research collaborations, and future technology directions to help organizations strengthen innovation strategies and intellectual property portfolios.

Key Coverage

Advanced packaging patent landscape

Patent filing trends

Technology domain analysis

Leading patent holders

Patent portfolio benchmarking

Geographic patent distribution

Citation analysis

Licensing landscape

White-space opportunities

Future patent outlook

Target Audience

Chief Intellectual Property Officers (CIPOs)

Intellectual Property & Patent Teams

Research & Development (R&D) Teams

Advanced Packaging Technology Developers

Innovation Management Teams

Technology Scouting Teams

Product Development Teams

Semiconductor Manufacturers

OSATs

Equipment Suppliers

Material Suppliers

Universities & Research Institutions

Government & Research Organizations

Technology Transfer Offices

Investment & Venture Capital Firms

Legal & Licensing Professionals

What This Report Offers

Comprehensive advanced packaging patent landscape assessment

Patent filing and publication trend analysis

Patent portfolio benchmarking

Leading patent holder and assignee analysis

Advanced packaging technology domain analysis

Geographic patent distribution assessment

Patent citation and quality analysis

Inventor and innovation activity assessment

Licensing and patent commercialization insights

Freedom-to-operate intelligence

Emerging innovation and white-space opportunity identification

Future intellectual property and technology outlook

Key Companies Covered (Illustrative)

TSMC

Samsung Electronics

Intel Corporation

ASE Technology Holding

Amkor Technology

JCET Group

Powertech Technology

Tongfu Microelectronics

UTAC Holdings

Nepes Corporation

Hana Micron

ChipMOS Technologies

KYEC

Unisem

Tessolve

FormFactor

And other leading patent holders and industry participants.

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